Invitation Letter

June 29, 2026

To:
Yang Liu
Hunan University Of Science And Technology, China
liuyang7740038@163.com

Dear Yang Liu,

On behalf of the Organizing Committee of the 32nd International Conference on Computational & Experimental Engineering and Sciences (ICCES2026), we are pleased to formally invite you to attend ICCES2026, which will be held in Hong Kong SAR, China, from August 7 to 12, 2026.

We are pleased to inform you that your paper entitled *"Interfacial Regulation and Strengthening-Toughening Behavior of TC4/Inconel 718 Dissimilar Materials Fabricated by Laser Directed Energy Deposition"* (ID: 15141) has been accepted for oral/poster presentation at the conference. Please complete your registration at your earliest convenience: www.iccesconf.org/registration.

We also encourage you to finalize your travel arrangements well in advance to ensure your full participation not only in presenting your paper, but also in engaging in the insightful technical discussions throughout the conference.

Should you require any further information, please feel free to contact the ICCES Secretariat.

Sincerely,

Zuankai Wang
Conference Chair, ICCES2026
Department of Mechanical Engineering
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Hong Kong SAR, China

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